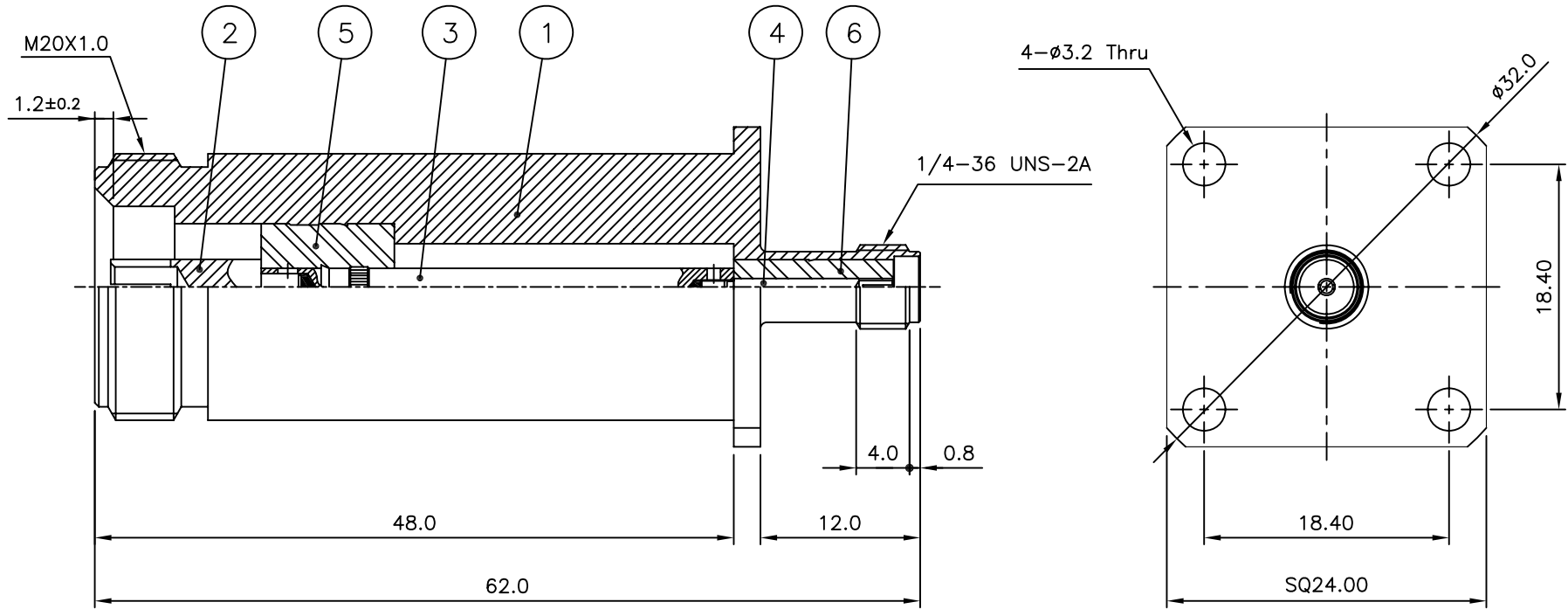


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	H.J.LEE	I.C.KIM	2015.04.30.
1	[설번No.201904-0001] PIN 이탈 개선으로 인한 편 변경	S.Y.EUN	I.C.KIM	2019.04.04.



* 조립 순서 *

1. ⑥ 번 TEFLON 조립
2. ⑤ 번 TEFLON 조립
3. PIN 조립

6	INSULATOR	1	TEFLON		DIN00123-N/1
5	INSULATOR	1	TEFLON		DIN02512-N/1
4	CONTACT	1	BeCu C17300	Silver Plate (5μm)	DCT03481-5/1
3	CONTACT	1	MBsBD C3604BD-F	Silver Plate (5μm)	DCT03478-5/2 DCT03478-5/1
2	CONTACT	1	BeCu C17300	Silver Plate (5μm)	DCT03330-5/1
1	BODY	1	MBsBD C3604BD-F	SUCCO Plate (5μm)	DAD00293-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2019. 04. 04.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL		CHECKED BY		KJ COMTECH CO.,LTD. TITLE 4.1/9.5 DIN50 (J) SMA50 (J) ADAPTOR
		DRAWN BY	S.Y.EUN	
FINISH		SCALE	2/1	A4 DWG NO. AD00557-7/1 REVISION 1 SHEET 1 of 1
		UNIT	mm	